

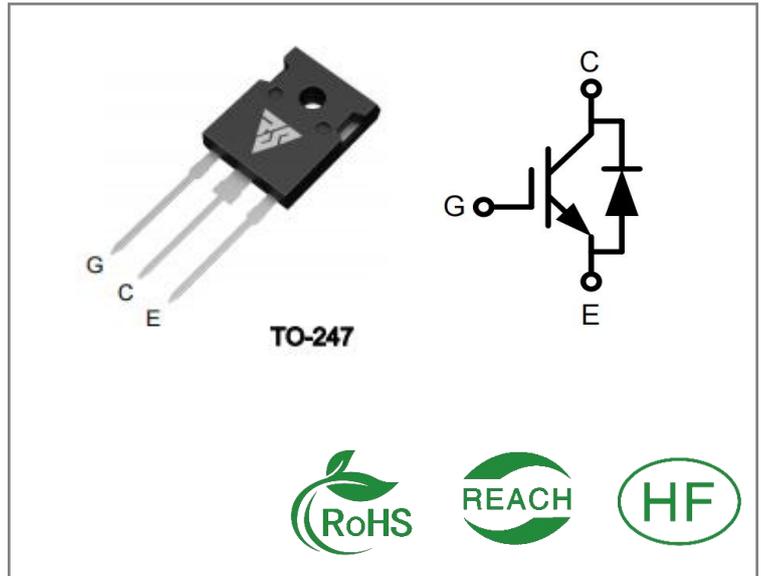
IF	V <sub>ce(sat)</sub>	VCES
50A	1.58V	650V

**Applications:**

- EV Charging
- Uninterruptible Power Supply (UPS)
- Inverters

**Features:**

- 650V trench gate/field termination process
- Very low V<sub>ce(sat)</sub>
- Low switching loss
- Positive temperature coefficient in V<sub>ce(sat)</sub>


**Ordering Information**

Part Number	Package	Marking	Packing	Qty.
RSG50N65HW	T0-247-3	RSG50N65HW	Tube	30 PCS

**Absolute Maximum Ratings** T<sub>c</sub>= 25°C unless otherwise specified

Symbol	Parameter	RSG50N65HW	Units
VCES	Collector-Emitter Voltage	650	V
VGES	Gate- Emitter Voltage	±20	V
IC	Continuous DC collector current TC = 100 °C	50	A
IC <sub>rm</sub>	Repetitive peak collector current tp=1 ms	100	A
P <sub>tot</sub>	Total Power Dissipation @ TC = 25°C	275	W
T <sub>stg</sub>	Operating Junction and Storage Temperature Range	-40 to 150	°C
TL	Maximum Temperature for Soldering	260	°C

**Thermal Characteristic**

Symbol	Parameter	RSG50N65HW	Units
R <sub>thJC</sub>	Thermal Resistance, Junction to case for IGBT	0.38	K/ W

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
<b>Static Characteristics</b>						
V(BR)CES	Collector-Emitter Breakdown Voltage	650	-	--	V	$V_{GE}=0V, I_{CE}=1mA$
ICES	Collector-Emitter Leakage Current	-	-	1	mA	$V_{GE}=0V,$ $V_{CE}=650V$
IGES	Gate to Emitter Leakage current	-	-	200	nA	$V_{GE}=+20V,$ $V_{CE}=0V$
VCE(sat)	Collector-Emitter Saturation Voltage	-	1.58	2.1	V	$I_C=50A$ $V_{GE}=15$ C
	Gate Threshold Voltage	-	1.95	--	V	V C
VGE(th)	Collector-Emitter Breakdown Voltage	4.2	5.0	5.8	V	$I_C=0.5mA, V_{CE}=V_{GE}$
Gfs	Transconductance		77		S	$I_C=50A, V_{CE}=20V$
<b>Dynamic Characteristics</b>						
Cies	Input Capacitance	-	5460	--	PF	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1MHz$
Coēs	Output Capacitance	-	200	--		
Cres	Reverse Transfer Capacitance	-	100	--		
Qg	Total Gate Charge		5.4		uC	$I_C = 50 A, V_{GE} = 15$ $V, V_{CE} = 520 V$
<b>Switching Characteristics</b>						
td(ON)	Turn-on Delay Time	-	33	--	ns	$V_{CE}=400V,$ $I_C=50A,$ $V_{GE}=+/-15V,$ $R_g=8\Omega,$ Inductive Load
t <sub>r</sub>	Rise Time	-	75			
td(OFF)	Turn-Off Delay Time	-	21	--		
t <sub>f</sub>	Fall Time	-	41	--		
E <sub>on</sub>	Turn-On Switching Loss	-	2.36	--	mJ	
E <sub>off</sub>	Turn-Off Switching Loss	-	0.6	--		

**Diode Maximum Ratings** (T<sub>J</sub>= 25°C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions
VRRM	Repetitive Peak Reverse Voltage	650	V	TC = 25°C
IF	Forward Current	50	A	TC = 100°C
IFRM	Repetitive Peak Forward Surge Current	100	A	tp=1 ms

**Characteristics Values** (T<sub>C</sub>=25°C unless otherwise noted)

Symbol	Parameter	Min.	Typ.	Max.	Test Conditions	Unit
VF	Forward Voltage		1.63 1.42 1.37	2.1	IF = 50A, V <sub>GE</sub> =0V T <sub>J</sub> = 25°C IF = 50A, V <sub>GE</sub> =0V T <sub>J</sub> = 125°C IF = 50A, V <sub>GE</sub> =0V T <sub>J</sub> = 150°C	V
IRM	Peak reverse recovery current		21 29 32		VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 25°C VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 125°C VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 150°C	A
Qrr	Reverse Recovery Charge		1.47 3.25 3.95		VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 25°C VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 125°C VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 150°C	uC
trr	Reverse Recovery time		132 198 217		VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 25°C VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 125°C VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 150°C	ns
Erec	Reverse recovered energy		0.37 0.65 0.77		VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 25°C VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 125°C VR = 400V, IF = 50A, V <sub>GE</sub> =-15V diF/dt=411A/us T <sub>J</sub> = 150°C	mJ
R <sub>thJC</sub>	Diode Thermal Resistance, Junction		0.45			K/ W
T <sub>vj op</sub>	Temperature under switching conditions	-40		175		°C

Typical Feature Curve

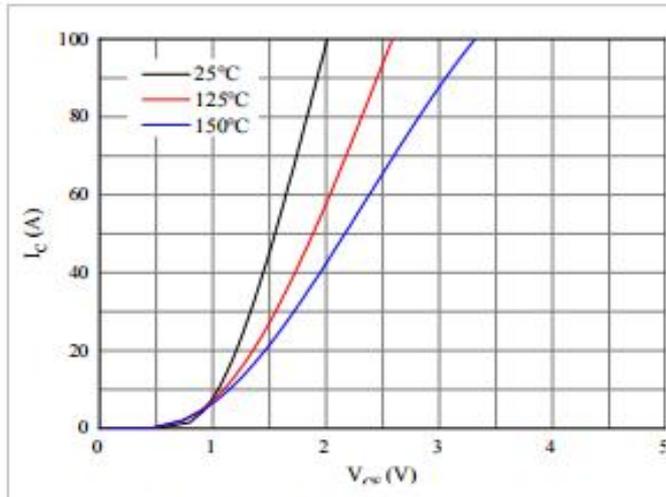


图 1. 典型输出特性 ( $V_{GE}=15V$ )

Figure 1. Typical output characteristics ( $V_{GE}=15V$ )

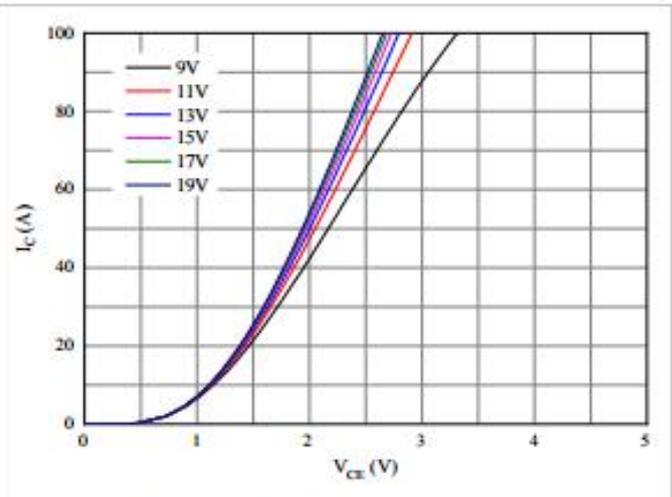


图 2. 典型输出特性 ( $T_{vj}=150^{\circ}C$ )

Figure 2. Typical output characteristics ( $T_{vj}=150^{\circ}C$ )

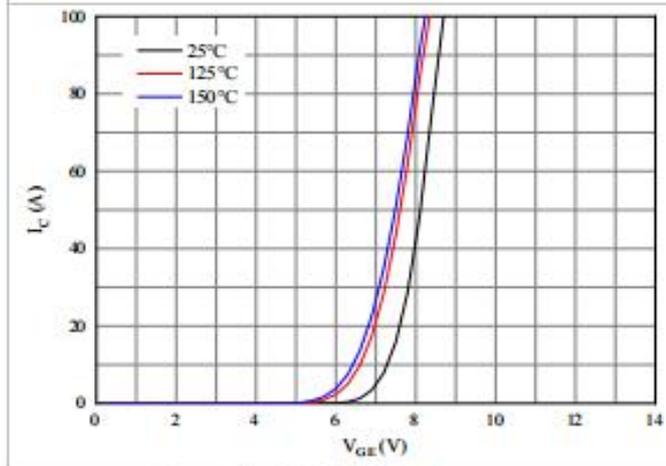


图 3. 典型传输特性 ( $V_{CE}=20V$ )

Figure 3. Typical transfer characteristic ( $V_{CE}=20V$ )

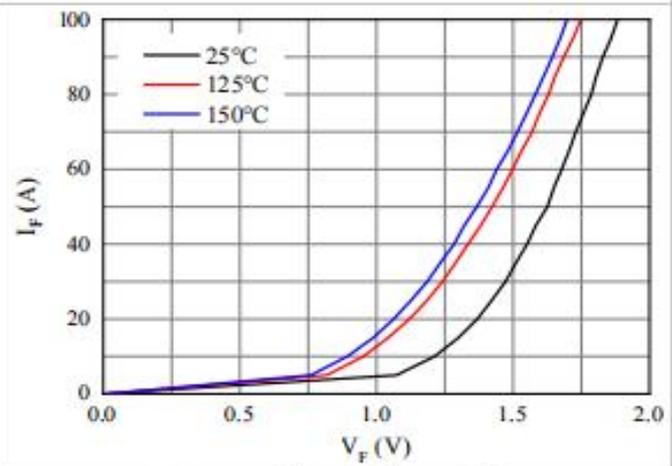


图 4. 正向偏压特性 二极管

Figure 4. Forward characteristic of Diode

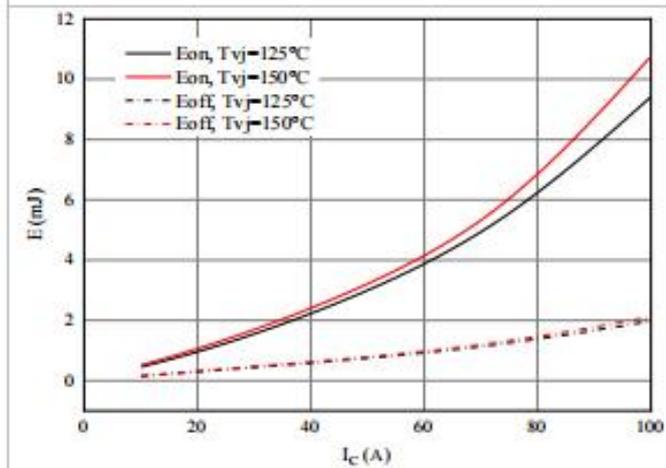


图 5. 开关损耗

Figure 5. Switching losses of IGBT

$V_{GE}=\pm 15V, R_{Gon}=8\Omega, R_{Goff}=8\Omega, V_{CE}=400V$

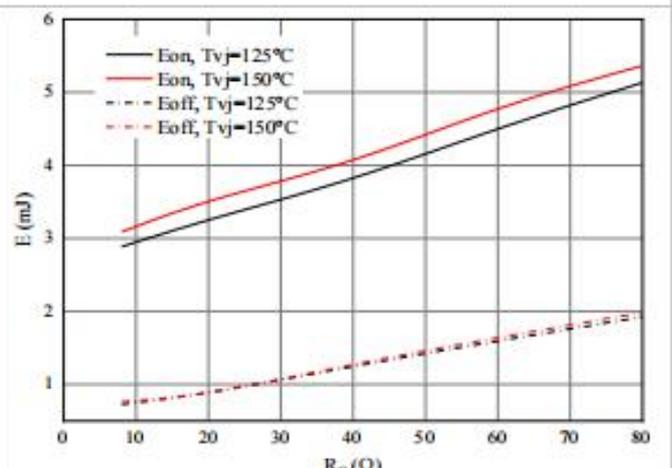


图 6. 开关损耗

Figure 6. Switching losses of IGBT

$V_{GE}=\pm 15V, I_C=50A, V_{CE}=400V$

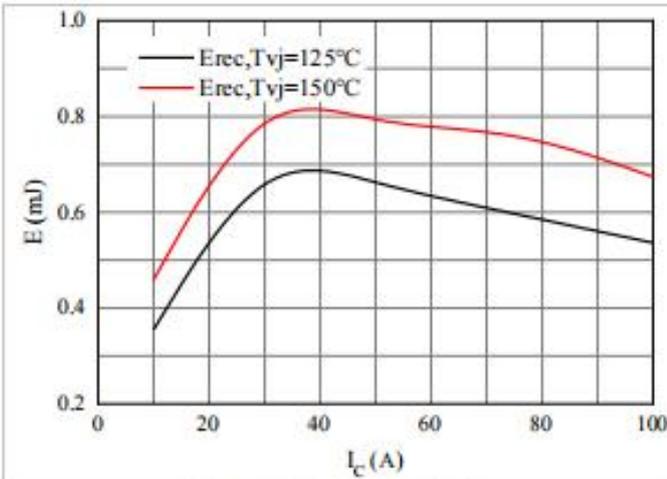


图 7. 开关损耗 二极管  
Figure 7. Switching losses of Diode  
 $R_{gon}=8\Omega, V_{CE}=400V$

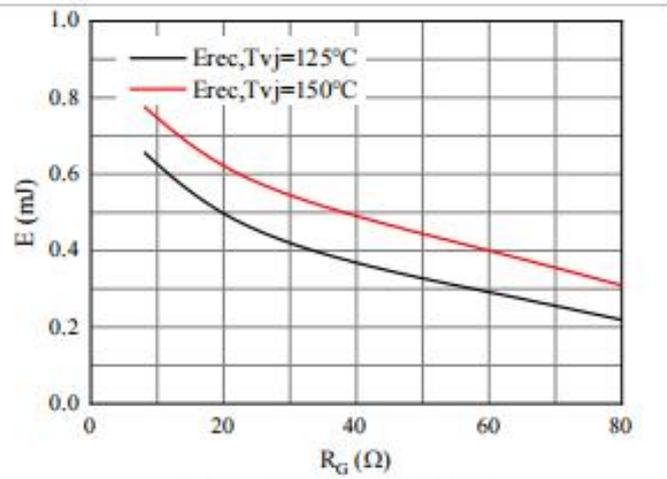


图 8. 开关损耗 二极管  
Figure 8. Switching losses of Diode  
 $I_F=50A, V_{CE}=400V$

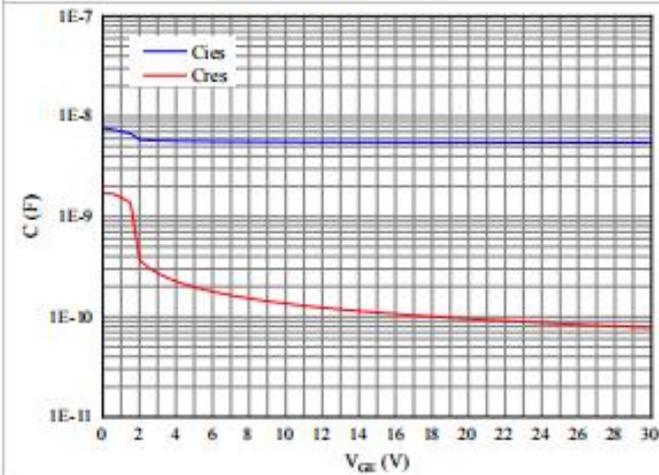
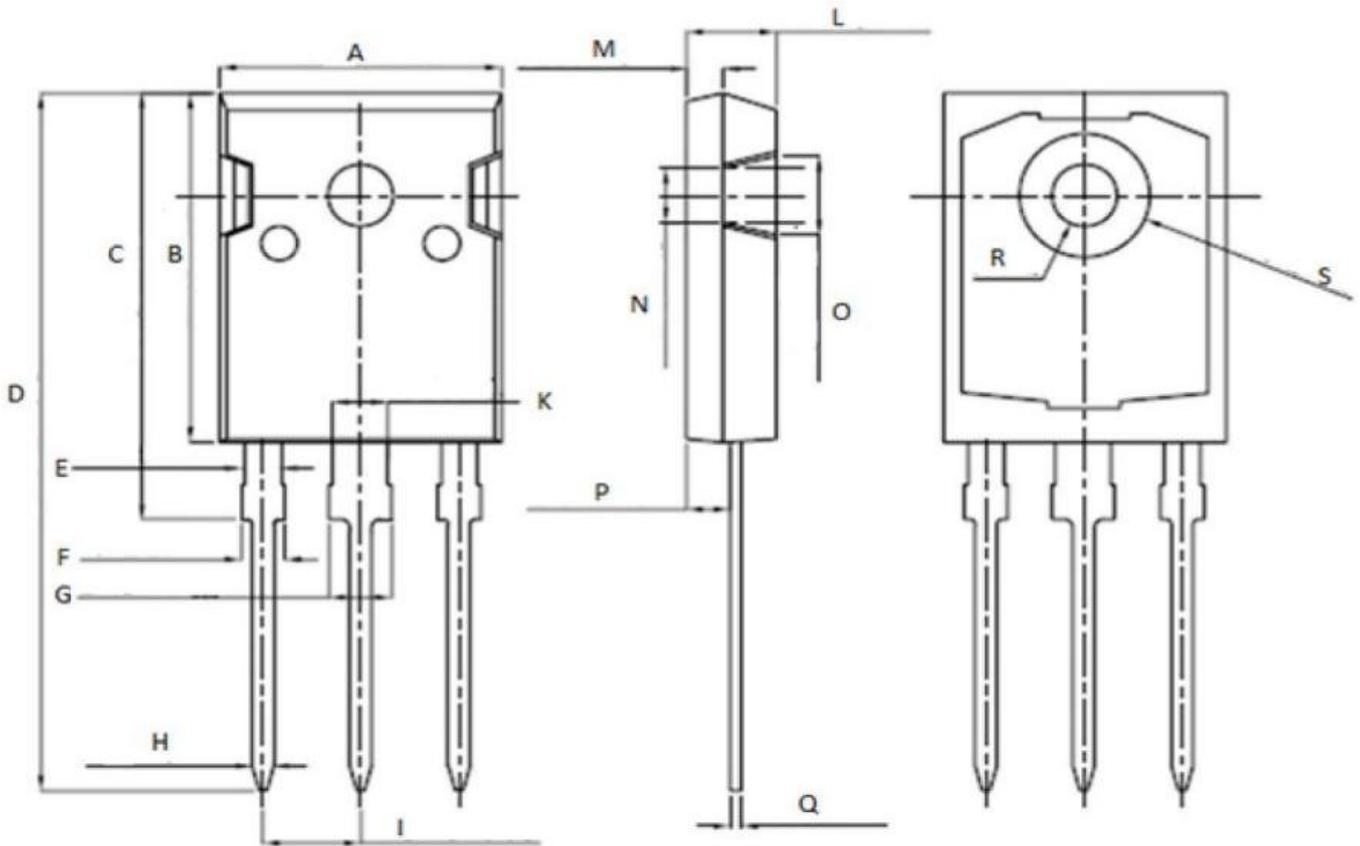


图 9. 电容特性  
Figure 9. Capacitance characteristic

Package outline drawing(TO-247-3 Unit: mm)



Unit: mm		
Symbol	Min.	Max.
A	15.95	16.25
B	20.85	21.25
C	20.95	21.35
D	40.5	40.9
E	1.9	2.1
F	2.1	2.25
G	3.1	3.25
H	1.1	1.3
I	5.40	5.50

Unit: mm		
Symbol	Min.	Max.
K	2.90	3.10
L	4.90	5.30
M	1.90	2.10
N	4.50	4.70
O	5.40	5.60
P	2.29	2.49
Q	0.51	0.71
R	φ 3.5	φ 3.7
S	φ 7.1	φ 7.3

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